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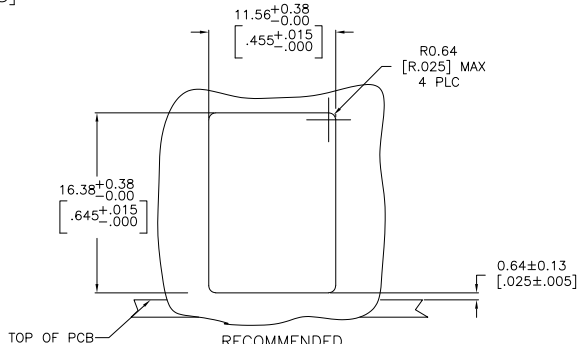
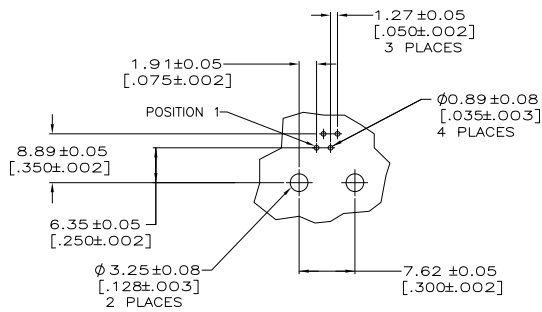
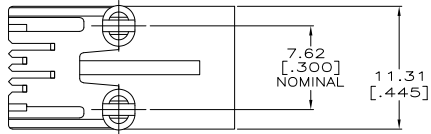
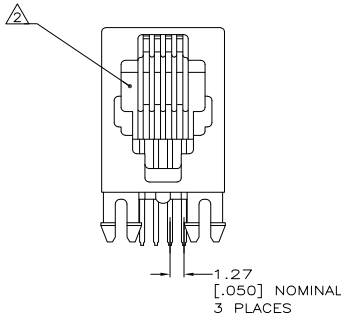
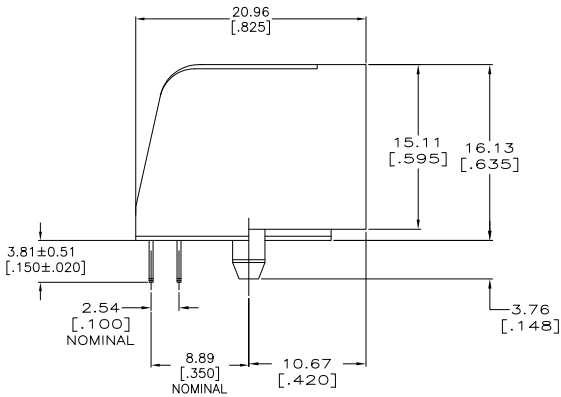
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LOC	DIST	REVISIONS			
F	LNK	DESCRIPTION	DATE	BY	APPD
AA	00				
	C1	REVISED PER ECO-11-005033	23MAR11	RK	HMR



- MATERIAL:
HOUSING - PBT POLYESTER, COLOR: BLACK
TERMINAL - 0.36[.014] THICK PHOS BRONZE PLATED WITH (SEE TABLE) MIN HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81µm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MIN THICK NICKEL UNDERPLATE
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.
- DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.
- 0.15µm[.000006] GOLD PLATED PARTS DO NOT MEET THE MINIMUM GOLD THICKNESS REQUIREMENT OF FCC SPECIFICATION, PART 68. PARTS HAVE NOT BEEN TESTED TO THE DURABILITY REQUIREMENTS OF TE CONNECTIVITY PRODUCT SPEC 108-1163

RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
COMPONENT SIDE SHOWN
SCALE 2:1

4	0.15µm [.000006]	2-5555980-2
	1.27µm [.000050]	5555980-1
	GOLD THICKNESS	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DRN G. ATTADIA - 09JAN2005	CHK D. DOCKES - 09JAN2005	TE Connectivity	
DIMENSIONS: mm [INCHES]		APPROVED BY: S. FLICKINGER		TE Connectivity	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		PART NO. 108-1163		NAME MODULAR JACK ASSEMBLY, SIDE ENTRY, 4 POSITION, FLANGELESS, WITHOUT PANEL STOPS	
0 PLC ± -		PRODUCT SPEC 114-2048		SIZE ONE CODE (DRAWING NO)	
1 PLC ± -		APPLICATION SPEC 114-2048		RESTRICTED TO	
2 PLC ± 0.1% (.005)		MATERIAL		A2 00779 C=5555980	
3 PLC ± -		FINISH		CUSTOMER DRAWING	
4 PLC ANGLES ± -		SEE NOTE 1		SCALE 1:1 SHEET 1 of 1 REV C1	

1471-9 (3/11)

5555980

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